

Title	Engineering Prototype Report for EP-86 – 6.6 W Multi-Class Powered Device (PD) for Power over Ethernet (PoE) Using DPA-Switch [®] (DPA423G)
Specification	Input: 33-57 VDC, Output: 3.3 V / 2.0 A
Application	PoE Class 2 PD – Including IEEE802.3af Compliant Interface Circuit
Author	Power Integrations Applications Department
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Summary and Features

- Meets IEEE802.3af requirements according to University of New Hampshire Interoperability Consortium (UNH-IOC) test results, for Class 1–3 PoE PDs
- DPA-Switch PWM controller with integrated 220 V power MOSFET switch
 - Under-voltage (UV) and overvoltage (OV) shutdown functions
 - Auto-recovering, hysteretic thermal shutdown
 - Auto-restart function: protects against short-circuit and open loop faults
 - No-load regulation achieved by cycle skipping
 - Fully integrated soft-start minimizes start-up stress and overshoot
 - Externally programmed I_{LIMIT} scales with V_{IN} for power limiting
 - Lossless MOSFET current sense eliminates external sensing components
- Small footprint 3.1" × 1", low overall height 0.45" (excluding RJ-45 connector)

The products and applications illustrated herein (including circuits external to the products and transformer construction) may be covered by one or more U.S. and foreign patents or potentially by pending U.S. and foreign patent applications assigned to Power Integrations. A complete list of Power Integrations' patents may be found at *www.powerint.com*.

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Important Note:

Although this board was designed to satisfy safety isolation requirements, it has not been agency approved. Therefore, please take the appropriate safety precautions.



1 Introduction

This engineering report describes a PoE power supply designed around the DPA423G. The supply can deliver 6.6 W continuously, from an input voltage range of 33 VDC to 57 VDC.

The following design information is provided: the power supply specification, circuit diagrams, a complete bill of materials, the results of the *PIXIs* spreadsheet file that was used to design the supply and detailed information on the design and construction of the transformer. Data and test results that document the performance of the supply under various line and load conditions are also included.



Figure 1 – Populated Circuit Board Top View.



Figure 2 – Populated Circuit Board Bottom View.



2 Power Supply Specification

Description	Symbol	Min	Тур	Max	Units	Comment
Input						
Voltage	V _{IN}	33	48	57	VDC	
Under-Voltage ON	$V_{IN_UV_ON}$			42	VDC	
Under-Voltage OFF	$V_{IN_UV_OFF}$	33			VDC	
Output						
Output Voltage 1	V _{OUT1}	3.135	3.3	3.465	V	± 5%
Output Ripple Voltage 1	V _{RIPPLE1}			35	mVp-p	20 MHz bandwidth
Output Current 1	I _{OUT1}	0		2	А	
Output Peak Current 1	I _{OUT1_PK}	2.5			A	
Total Output Power						
Average Output Power	P _{OUT1}		6.6		W	
Average Output Power	POUT_FAULT	8.6			W	R6 = 10.2 Ω
Full Load Efficiency	η		73		%	
Environmental						
Conducted EMI		Meets CISPR22B / EN55022B				
Safety		Designed to meet IEC950, UL1950 Class II			UL1950	
Ambient Temperature	T _{AMB}	0		40	°C	



3 Schematic





4 Circuit Operation

4.1 General

A flyback topology was used to minimize circuit board size, parts count and cost. This topology also provides excellent operating efficiency across the input voltage range.

4.2 DPA-Switch Primary

The DPA423G IC implements PWM control of the internal power MOSFET and initiates a soft start-up function when it first powers up. The IC also monitors die temperature as part of its over-temperature protection function and also monitors the input voltage as part of its under-voltage detection and overvoltage shutdown functions. The integrated 220 V MOSFET provides excellent switching characteristics at the selected 400 kHz operating frequency. The MOSFET and controller consume very little power, giving good efficiency across the entire input voltage operating range.

Diodes D3 through D9 ensure that the incoming DC input voltage is correctly polarized. Capacitors C1 and C2 and inductor L1 form a low-cost pi (π) filter that attenuates conducted EMI noise, to keep it from being passed to the incoming line.

Resistors R4 and R6 program the internal current limit of the DPA423G, so that it reduces as the input voltage increases. This helps to keep the variance of the maximum output overload current below 5%, across the entire input voltage range.

The IC's integrated MOSFET is protected from overvoltage stresses that could damage it (during a line surge) by a primary-side Zener diode clamp (VR3). Zener diode VR3 does not conduct under normal operating conditions.

The primary bias winding provides CONTROL pin current after start-up. Diode D2 rectifies the bias winding voltage, while R8 and C11 attenuate high frequency switching noise and reduce the peak charging of the bias voltage.

4.3 Output Rectification

The secondary winding voltage is rectified by a low-loss Schottky diode (D11). Low ESR, tantalum output capacitors, C7 and C8, filter the output voltage. The LC output filter (L2, C9 and C10) further attenuates switching noise and ripple from the output voltage.

4.4 Output Feedback

Resistor divider (R12 and R13) senses the output voltage and feeds it into the reference pin of a 1.24 V reference IC (U4). The conduction of U4 pulls current through the LED of optocoupler U5, which controls the conduction of its phototransistor (U5-B). The phototransistor modulates the current that flows into the CONTROL pin of U1. Since the *DPA-Switch* is a current-to-duty-cycle converter, it uses the varying CONTROL pin current to pulse-width modulate the duty cycle of the MOSFET switch. Resistor R10 sets the gain of U4, while R11 and C13 compensate for the variation in gain of U4 over the frequency range of the feedback loop's bandwidth (about 10 kHz). Feedback



compensation is required to ensure stable operation of the supply and optimum response to line and load transients. Capacitor C12 performs a soft-finish function that prevents the output voltage from overshooting the regulation set point during initial startup of the converter.

4.5 PoE Interface Circuit Description

See DI-88 for a full description. Resistor R26 provides the correct impedance for the detection phase of PD operation.



Figure 4 – Detection Impedance V-I curve.

The classification circuit is enabled when Zener diode VR6 conducts (above 11 VDC). Transistor Q9 controls the bias current source programmed to approximately 350 μ A by resistor R21. This bias current source provides the minimum operating current to voltage reference IC U6. The main classification current flowing through R20 generates a voltage that is referenced to the internal reference (1.24 VDC) of U6 and that later closes the loop by controlling the base drive of Q7. The value of the classification current source is determined by the value of the voltage on the reference pin of U6 divided by the value of R20 in ohms.



Class	Р _{олт} (min)	Р _{олт} (max)	l _{c∟} (min)	I _{c∟} (max)	R34
	W	W	mA	mΑ	Ohms
0	0.44	12.95	0.5	4	-
1	0.44	3.84	9	12	133
2	3.84	6.49	17	20	69.8
3	6.49	12.95	26	30	45.3

Figure 5 – Table of PoE Classifications and Power Levels.



Figure 6 – Classification Current (Class 2: R34 = 69.8 Ω ; Class 3: R34 = 45.3 Ω).

Zener diode VR5 conducts above 27 VDC, raising the gate voltage on the pass-switch MOSFET (Q8), turning it on when the gate-threshold voltage is exceeded. Pull-down resistor R25 limits the current through VR5 while pull-down resistor R24 keeps Q8 turned off, unless it is being actively driven on. Zener diode VR4 limits the maximum gate-to-source voltage on Q8 to 15 V. When VR5 conducts, it also turns on Q6 through R23. Transistor Q6 pulls down on the base of Q7, which turns off the main classification current source (although the bias current source of 350 µA will continue to conduct).

4.6 Wide Hysteresis Under-Voltage Lockout

If there were no other components connected to the L pin, then resistor R5 would set the under-voltage turn-on threshold to approximately 35 VDC and the turn-off threshold to approximately 33 VDC.

However, in the case of PoE, the turn-on voltage is much higher than the turn-off voltage. This requires more under-voltage hysteresis. When the power supply is operating normally, the bias voltage is approximately 14 VDC. Resistors R15 and R16 form a voltage divider that turns off the base of Q2, once the DC-DC converter has begun switching and the bias voltage is present. At start-up, when the bias voltage is absent,



Q2 is on, and sinks additional current from the resistor (R5) that connects the L pin to the DC input voltage. The value of R14 was selected so that an extra 10 μ A is drawn at startup, which increases the turn-on threshold voltage to 41 VDC typical. However, because Q2 turns off after start-up, the UV turn-off threshold stays at 34 VDC (see DI-101 for more details).



Figure 7 – L-pin current without and with the widened UV hysteresis circuit.



5 Bill of Materials

Item	Qty.	Ref.	Description	Mfg Part Number	Mfg
1	2	C1, C2	470 nF, 100 V, Ceramic, X7R, 1210	ECJ-4YB2A474K	Panasonic
2	1	C3	47 pF, 100 V, Ceramic, NPO, 0603	06031A470JAT2A	AVX
3	1	C4	1000 pF, 1500V, 1808	1808SC102KAT1A	AVX
4	2	C5, C13	100 nF 25 V, Ceramic, X7R, 0603	ECJ-1VB1E104K	Panasonic
5	1	C6	22 μF, 10 V, Tant Electrolytic, SMD	TAJA226K010R	Kemet
6	3	C7, C8, C9	330 μF, 6.3 V, Tant Electrolytic, SMD	T495X337K006AS	Kemet
7	1	C10	1 μF, 16 V, Ceramic, X5R, 0603	GRM188R61C105KA 93D	Murata
8	1	C11	1 μF, 25 V, Ceramic, X7R, 1206	ECJ-3YB1E105K	Panasonic
9	1	C12	220 nF, 25 V, Ceramic, X7R, 0603	06033D224KAT2A	AVX
10	1	D2	75 V, 0.2 A, Fast Switching, 50 ns, SOD- 323	1N4148WS-7	Diode Inc.
11	8	D3, D4, D5, D6, D7, D8, D9, D10	100 V, 1 A, Rectifier, Glass Passivated, DO- 213AA (MELF)	DL4002	Diodes Inc
12	1	D11	20 V, 4 A, Schottky, SMD, DO-214AB	SL42-9B	Vishay
13	1	J1	R/A, RJ45 Non-shielded, PCBM	RJHS-5080	Amphenol Canada
14	2	J2-1, J2-2	Zierick output pins		Zierick
15	1	L1	10 μH, 0.85 A	HM79-10100LFTR7	B.I.Technologies
16	1	L2	1 μH, 1.9 A	HM79-101R0LFTR7	B.I.Technologies
17	1	Q2	PNP, Small Signal BJT, 40 V, 0.2 A, SOT- 323	MMST3906-7	Diodes Inc
18	3	Q4, Q5, Q7	NPN, Small Signal BJT, 80 V, 0.5 A, SOT- 23	MMBTA06LT1	On Semiconductor
19	1	Q6	NPN, Small Signal BJT, 40 V, 0.2 A, SOT- 323	MMST3904	Diodes Inc
20	1	Q8	100 V, 1.15 A, 250 mΩ, N-Channel, SOT-23	SI2328DS	Vishay
21	1	R4	1.00 MΩ, 1%, 1/16 W, Metal Film, 0603	ERJ-3EKF1004V	Panasonic
22	1	R5	649 kΩ, 1%, 1/8 W, Metal Film, 0805	ERJ-6ENF6493V	Panasonic
23	1	R6	10.00 kΩ, 1%, 1/16 W, Metal Film, 0603	ERJ-3EKF1002V	Panasonic
24	1	R7	10 Ω, 5%, 1/10 W, Metal Film, 0603	ERJ-3GEYJ100V	Panasonic
25	1	R8	100 Ω, 1%, 1/16 W, Metal Film, 0603	ERJ-3EKF1000V	Panasonic
26	1	R9	5.1 Ω, 5%, 1/10 W, Metal Film, 0603	ERJ-3GEYJ5R1V	Panasonic
27	1	R10	75 Ω, 5%, 1/10 W, Metal Film, 0603	ERJ-3GEYJ750V	Panasonic
28	1	R11	1 kΩ, 5%, 1/10 W, Metal Film, 0603	ERJ-3GEYJ102V	Panasonic
29	1	R12	33.2 kΩ, 1%, 1/8 W, Metal Film, 0805	ERJ-6ENF3322V	Panasonic



30 1 R13 20 kΩ, 5%, 1/10 W, Metal Film, 0603 ERJ-3GEYJ203V Panas 31 1 R14 174 kΩ, 1%, 1/16 W, Metal Film, 0603 ERJ-3EKF1743V Panas 32 1 R15, R16 10 kΩ, 5%, 1/10 W, Metal Film, 0603 ERJ-3GEYJ103V Panas 35 1 R20 69.8 Ω, 1%, 1/16 W, Metal Film, 0603 ERJ-3GEYJ103V Panas 36 1 R21 2 kΩ, 5%, 1/10 W, Metal Film, 0603 ERJ-3GEYJ202V Panas 37 2 R22, R23 100 kΩ, 5%, 1/10 W, Metal Film, 0603 ERJ-3GEYJ104V Panas 38 1 R24 220 kΩ, 5%, 1/10 W, Metal Film, 0603 ERJ-3GEYJ224V Panas 39 1 R25 51 kΩ, 5%, 1/10 W, Metal Film, 0603 ERJ-3GEYJ513V Panas 40 1 R26 24.9 kΩ, 1%, 1/8 W, Metal Film, 0805 ERJ-6ENF2492V Panas 40 1 R26 24.9 kΩ, 1%, 1/8 W, Metal Film, 0805 ERJ-6ENF2492V Panas 41 1 T1 Bobbin, ER14.5/6, Horizontal, 10 pins, SMD SIL6029 LiS	sonic sonic sonic sonic sonic sonic sonic sonic sonic sonic sonic sonic sonic sonic
32 1 R15, R16 10 kΩ, 5%, 1/10 W, Metal Film, 0603 ERJ-3GEYJ103V Panas 35 1 R20 69.8 Ω, 1%, 1/16 W, Metal Film, 0603 ERJ-3EKF69R8V Panas 36 1 R21 2 kΩ, 5%, 1/10 W, Metal Film, 0603 ERJ-3GEYJ202V Panas 37 2 R22, R23 100 kΩ, 5%, 1/10 W, Metal Film, 0603 ERJ-3GEYJ104V Panas 38 1 R24 220 kΩ, 5%, 1/10 W, Metal Film, 0603 ERJ-3GEYJ202V Panas 39 1 R25 51 kΩ, 5%, 1/10 W, Metal Film, 0603 ERJ-3GEYJ202V Panas 40 1 R26 24.9 kΩ, 1%, 1/10 W, Metal Film, 0603 ERJ-3GEYJ513V Panas 40 1 R26 24.9 kΩ, 1%, 1/8 W, Metal Film, 0805 ERJ-6ENF2492V Panas 41 1 T1 Bobbin, ER14.5/6, Horizontal, 10 pins, SMD ERJ-30825 LiSI SNX1393 Santro YC-1404S Ying Ying	sonic sonic sonic sonic sonic sonic sonic sonic sonic sonic sonic raft
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36 1 R21 2 kΩ, 5%, 1/10 W, Metal Film, 0603 ERJ-3GEYJ202V Panas 37 2 R22, R23 100 kΩ, 5%, 1/10 W, Metal Film, 0603 ERJ-3GEYJ104V Panas 38 1 R24 220 kΩ, 5%, 1/10 W, Metal Film, 0603 ERJ-3GEYJ224V Panas 39 1 R25 51 kΩ, 5%, 1/10 W, Metal Film, 0603 ERJ-3GEYJ513V Panas 40 1 R26 24.9 kΩ, 1%, 1/8 W, Metal Film, 0805 ERJ-6ENF2492V Panas 41 1 T1 Bobbin, ER14.5/6, Horizontal, 10 pins, SMD SIL6029 Hito 41 1 T1 Bobbin, ER14.5/6, Horizontal, 10 pins, SMD SIL6029 Hito 41 1 T1 Bobbin, ER14.5/6, Horizontal, 10 pins, SMD SIL6029 Hito	sonic sonic sonic sonic sonic sonic nologies raft
37 2 R22, R23 100 kΩ, 5%, 1/10 W, Metal Film, 0603 ERJ-3GEYJ104V Panas 38 1 R24 220 kΩ, 5%, 1/10 W, Metal Film, 0603 ERJ-3GEYJ224V Panas 39 1 R25 51 kΩ, 5%, 1/10 W, Metal Film, 0603 ERJ-3GEYJ513V Panas 40 1 R26 24.9 kΩ, 1%, 1/8 W, Metal Film, 0805 ERJ-6ENF2492V Panas 40 1 R26 24.9 kΩ, 1%, 1/8 W, Metal Film, 0805 ERJ-6ENF2492V Panas 41 1 T1 Bobbin, ER14.5/6, Horizontal, 10 pins, SMD HM00-A5861LF DA2062-ALD LSTA30825 B.I Techn Coild SIL6029 41 1 T1 Bobbin, ER14.5/6, Horizontal, 10 pins, SMD SIL6029 VC-1404S LiSt	conic conic conic conic conic nologies raft
38 1 R24 220 kΩ, 5%, 1/10 W, Metal Film, 0603 ERJ-3GEYJ224V Panas 39 1 R25 51 kΩ, 5%, 1/10 W, Metal Film, 0603 ERJ-3GEYJ513V Panas 40 1 R26 24.9 kΩ, 1%, 1/8 W, Metal Film, 0805 ERJ-6ENF2492V Panas 40 1 R26 24.9 kΩ, 1%, 1/8 W, Metal Film, 0805 ERJ-6ENF2492V Panas 41 1 T1 Bobbin, ER14.5/6, Horizontal, 10 pins, SMD SIL6029 Hit 41 1 T1 Bobbin, ER14.5/6, Horizontal, 10 pins, SMD SIL6029 LiSI 50 VC-1404S Ying Ying Ying	sonic sonic sonic nologies raft
39 1 R25 51 kΩ, 5%, 1/10 W, Metal Film, 0603 ERJ-3GEYJ513V Panas 40 1 R26 24.9 kΩ, 1%, 1/8 W, Metal Film, 0805 ERJ-6ENF2492V Panas 40 1 R26 24.9 kΩ, 1%, 1/8 W, Metal Film, 0805 ERJ-6ENF2492V Panas 41 1 T1 Bobbin, ER14.5/6, Horizontal, 10 pins, SMD SIL6029 Hito 41 1 T1 Bobbin, ER14.5/6, Horizontal, 10 pins, SMD SIL6029 LiSI SNX1393 Santra YC-1404S Ying Ying	onic onic ologies raft
40 1 R26 24.9 kΩ, 1%, 1/8 W, Metal Film, 0805 ERJ-6ENF2492V Panas 41 1 T1 Bobbin, ER14.5/6, Horizontal, 10 pins, SMD HM00-A5861LF DA2062-ALD B.I Techn DA2062-ALD B.I Techn Coild SIL6029 41 1 T1 Bobbin, ER14.5/6, Horizontal, 10 pins, SMD SMD SNX1393 Santro YC-1404S	onic iologies raft
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411T1Bobbin, ER14.5/6, Horizontal, 10 pins, SMDDA2062-ALDCoild SIL6029411T1Bobbin, ER14.5/6, Horizontal, 10 pins, SMDSIL6029Hid SIL6029LSTA30825LiSISNX1393Santra Ying	raft
	nin onics
42 1 U1 DPA-Switch, DPA423G, SMD-8 DPA423G Power Inter	grations
43 1 U4 85 °C, SOT23-5 LMV431AIM5 Nation	-
44 1 Optocoupler, 80 V, CTR 200-400%, 4-Mini PC357N3T Sha	rp
45 1 U6 85 °C, SOT23-5 LMV431AIM5 Nation	-
46 1 VR3 150 V, 5 W, 5%, DO214AC (SMB) SMBJ150A Diode	s, Inc
47 1 VR4 15.0 V, 5%, 150 mW, SOD-323 BZT52C15T-7 Diode	s, Inc
48 1 VR5 27.0 V, 5%, 150 mW, SOD-323 MAZS2700ML Panasor	ic-SSG
49 1 VR6 11 V, 5%, 500 mW, DO-213AA (MELF) ZMM5241B-7 Diode	1
50 1 - PCB, EP-86, REV B	s Inc



6 Layout



Figure 8 – PCB Layout Top Side.Figure 9 – PCB Layout Bottom Side.



7 Transformer Design Spreadsheet

DCDC_DPASwitch_Flyback_071405; Rev.2.7; Copyright Power Integrations 2005	INPUT	INFO	OUTPUT	UNITS	DPASwitch_Flyback_071405 - Continuous/Discontinuous mode Spreadsheet. Copyright 2005 Power Integrations
ENTER APPLICATION VARIABLES				00	DC-DC Converter
	36			Volts	Minimum DC Input Voltage
VDCMAX	57			Volts	Maximum DC Input Voltage
VO	3.3			Volts	Output Voltage (main)
				VOILO	Verify temperature rise for continuous power. P and G
PO	6.6	Comment		Watts	packages may be thermally limited
n	0.8			maile	Efficiency Estimate
Z			0.7		Loss Allocation Factor, (0.7 Recommended)
	-		0.7		
VB	14			Volts	Bias Voltage (Recommended between 12V and 18V)
	1 1			V0113	Dias voltage (Recommended between 12 v and 10 v)
UV AND OV PARAMETERS					
		min	max		
VUVOFF		30.0		Volts	Minimum undervoltage On-Off threshold
VUVON		32.2		Volts	Maximum undervoltage Off-On threshold (turn-on)
VOVON		74.9	-	Volts	Minimum overvoltage Off-On threshold
VOVOFF		74.0		Volts	Maximum overvoltage On-Off threshold (turn-off)
RL				k-Ohms	
			013.0	K-Onina	
ENTER DPASWITCH VARIABLES					
DPASWITCH	DPA423G			16VDC	36 VDC
Chosen Device	DPA423G		Power OL	6W	13W
ILIMITMAX	1.16	1.34	FOWEI OL	Amps	From DPASWITCH Data Sheet
Frequency	L. 10	1.54		Лпра	Enter 'F' for fS = 400KHz and 'L' for fS = 300KHz
fS	375000			Hertz	DPASWITCH Switching Frequency
VOR	375000		20	Volts	Reflected Output Voltage
KI	0.7		0.7	VUIIS	Current Limit Reduction Factor
ILIMITEXT	0.7			Amps	Minimum External Current limit
			0.012	лпръ	Resistor from X pin to source to set external current
RX			11.0	k-Ohms	limit
VDS	1		11.0	Volts	DPASWITCH on-state Drain to Source Voltage
VD	0.5			Volts	Output Winding Diode Forward Voltage Drop
VDB	0.5			Volts	Bias Winding Didde Forward Voltage Drop
VDB	- 0.7			VUIIS	Ripple to Peak Current Ratio (0.2 < KRP < 1.0 : 1.0 <
KRP/KDP	0.62				KDP<6.0)
	0.02				
ENTER TRANSFORMER CORE/CONST	PUCTION		FS		
Core Type	ER14.5				
Core Manuf	LITT.J				
Bobbin Manuf					
				D/M	
Core		ER14.5	h h in	P/N:	ER14.5-3F3-S
Bobbin	1	ER14.5_Bo		P/N:	CPVS-ER14.5-1S-10P
AE	-		0.176		Core Effective Cross Sectional Area
				cm	Core Effective Path Length
AL	-			nH/T^2	Ungapped Core Effective Inductance
BW	-		1.9	mm	Bobbin Physical Winding Width
					Safety Margin Width (Half the Primary to Secondary
M	0			mm	Creepage Distance)
	2				Number of Primary Layers
NS	2				Number of Secondary Turns
				l	



CURRENT WAVEFORM SHAPE PARAMETERS			
DMAX	0.52		Maximum Duty Cycle
IAVG	0.23	Amps	Average Primary Current
IP	0.64	Amps	Peak Primary Current
IR	0.40	Amps	Primary Ripple Current
IRMS		Amps	Primary RMS Current
		•	
TRANSFORMER PRIMARY DESIGN PARAMETERS			
LP	119	uHenries	Primary Inductance
NP	20		Primary Winding Number of Turns
NB	8		Bias Winding Number of Turns
ALG	297	nH/T^2	Gapped Core Effective Inductance
			Peak Flux density during transients (Limit to 3000
BP	2739	Gauss	Gauss)
BM	2152	Gauss	Maximum Flux Density
			AC Flux Density for Core Loss Curves (0.5 X Peak to
BAC	667	Gauss	Peak)
ur	1203		Relative Permeability of Ungapped Core
LG	0.06	mm	Gap Length (Lg >> 0.051 mm)
BWE		mm	Effective Bobbin Width
	0.0		
TRANSFORMER SECONDARY DESIGN PARAMETERS			
ISP	6.38	Amps	Peak Secondary Current
ISRMS		Amps	Secondary RMS Current
10		Amps	Power Supply Output Current
IRIPPLE		Amps	Output Capacitor RMS Ripple Current
VOLTAGE STRESS PARAMETERS			
			Maximum Drain Voltage (Includes Effect of Leakage
VDRAIN	157	Volts	Inductance)
PIVS	9	Volts	Output Rectifier Maximum Peak Inverse Voltage
PIVB	36	Volts	Bias Rectifier Maximum Peak Inverse Voltage
ADDITIONAL OUTPUTS			
V_OUT2		Volts	2nd Output Voltage
VD_OUT2		Volts	2nd Output - Diode Forward voltage
N_OUT2	0.00		2nd Output - Turns
PIV_OUT2	0	Volts	2nd Output - Diode Peak Inverse Voltage
V_OUT3		Volts	3rd Output Voltage
VD_OUT3		Volts	3rd Output - Diode Forward voltage
N_OUT3	0.00		3rd Output - Turns
PIV_OUT3	0	Volts	3rd Output - Diode Peak Inverse Voltage
I_OUT2		Amps	2nd Output - Output Current
I_OUT3		Amps	3rd Output - Output Current
			If negative output exists enter Output number; eg: If
Negative Output	N/A		VO2 is negative output, enter 2



8 Transformer Specification

8.1 Transformer Winding



Figure 10 – Transformer Electrical Diagram.

8.2 Electrical Specifications

Electrical Strength	1 second, 60 Hz, from Pins 1-5 to Pins 6-10	1500 VDC
Primary Inductance	Pins 1-3, all other windings open	120 μH, ±10%
Resonant Frequency	Pins 1-3, all other windings open	7.5 MHz (Min.)
Primary Leakage Inductance	Pins 1-3, with Pins 6/7-9/10 shorted	3.0 μH (Max.)

8.3 Materials

Item	Description
[1]	Core: ER14.5, Ferroxcube 3C96, 3F3 (or equivalent), A _{LG} = 312 nH/T ²
[2]	Bobbin: ER14.5, 10 pin
[3]	Magnet Wire: #34 AWG, Double Coated (Heavy Nyleze)
[4]	Magnet Wire: #28 AWG, Double Coated (Heavy Nyleze)
[5]	Tape: 3M 1298 Polyester Film (or equivalent), 1.8 mm wide
[6] (optional)	Core Clamp ER14.5 Ferroxcube CLM14.5
[7]	Varnish (DIPPED ONLY, NOT VACUUM IMPREGNATED)



8.4 Transformer Build Diagram



Figure 11 – Transformer Build Diagram.

8.5 Transformer Construction

Bobbin Preparation	Arrange bobbin & rotation such that primary start/finish wires do not overlap.				
W1	Start at Pin 3. Wind 10 turns of item [3] in 1 layer. Bring finish lead back and terminate on Pin 2.				
W2 Starting at Pin 4, wind 8 turns of item [3]. Spread turns evenly across bobbin in a single layer. Bring finish lead back and terminate on Pin 5.					
Таре	Use one layer of item [5] for basic insulation.				
W3 Start at Pins 9 and 10. Wind 2 turns of bifilar item [4] in 1 layer. Bring finish lead back and terminate on Pins 6 and 7.					
Таре	Use one layer of item [5] for basic insulation.				
W4	Continue from Pin 2. Wind 10 turns of item [3] in 1 layer. Bring finish lead back and terminate on Pin 1.				
Outer Wrap	Outer Wrap Use one layer of item [5] for basic insulation.				
Final Assembly	Assemble and secure (glue or clamp, item [6]) core halves. Dip varnish item [7] and cure.				



9 Performance Data

All measurements were taken at room temperature utilizing a DC input source and DC dynamic loads (except where resistive loads are specified). Input and output voltages and current were measured with dedicated digital multi-meters (DMMs).

9.1 Efficiency



Figure 12 – Efficiency vs. Line and Load, Room Temperature.



9.2 Load Regulation



Figure 13 – Load Regulation, Room Temperature.

9.3 Line Regulation







9.4 Overload Output Current

The DC output load current was recorded just prior to the auto-restart operation at various input line voltages. Performance was measured for various values of resistor R6.



Figure 15 – Overload Output Current vs. Line Voltage for Different Values of R6, Room Temperature.



10 Waveforms

10.1 Drain Voltage and Current, Full-Load Operation



Figure 16 – 36 VDC, Full Load. Upper: I_{DRAIN} , 0.5 A / div. Lower: V_{DRAIN} , 50 V, 1 μ s / div.

10.2 Output Voltage Start-Up Profile



Figure 18 – Start-Up Profile, 36 VDC, No Load (worst-case). Upper: V_{OUT} , 1 V / div. Lower: V_{DRAIN} , 50 V, 1 μ s / div.



Figure 17 – 57 VDC, Full Load. Upper: I_{DRAIN} , 0.5 A / div. Lower: V_{DRAIN} , 50 V, 1 µs / div.



Figure 19 – Start-Up Profile, 57 VDC, No Load (worst-case). Upper: V_{OUT} , 1 V / div. Lower: V_{DRAIN} , 50 V, 1 μ s / div.



10.3 Load Transient Response (75% to 100% Load Step)

In the figures shown below, signal averaging was used to better enable viewing of the load transient response. The oscilloscope was triggered using the load current step as a trigger source. Since the output switching is random with respect to the load transient, contributions to the output ripple from these sources will average out, leaving the contribution only from the load step response.







Figure 21 – Transient Response, 57 VDC, 75-100-75% Load Step. Upper: Load Current, 1 A / div. Lower: Output Voltage, 20 mV, 500 μs / div.



10.4 Output Ripple Measurements

10.4.1 Ripple Measurement Technique

For DC output ripple measurements, a modified oscilloscope test probe must be utilized in order to reduce spurious signal pickup. Details of the probe modification are provided in Figures 22 and 23.

The 5125BA probe adapter is affixed with two capacitors tied in parallel across the probe tip. The capacitors include one (1) 0.1 μ F/50 V ceramic type and one (1) 1.0 μ F/50 V aluminum electrolytic. *Since the aluminum electrolytic type capacitor is polarized, proper polarity must be observed when connecting it to the output (see below).*



Figure 22 – Oscilloscope Probe Prepared for Ripple Measurement (End cap and ground lead removed).



Figure 23 – Oscilloscope Probe with Probe Master 5125BA BNC Adapter (Modified with wires for probe ground for ripple measurement, and two parallel decoupling capacitors added).



10.4.2 Output Ripple Measurements



Figure 24 – Ripple, 36 VDC, Full Load. Upper: 50 μ s / div, 10 mV / div. Lower: 2 μ s / div, 10 mV / div.



 $\begin{array}{l} \mbox{Figure 26}-\mbox{Ripple, 57 VDC, Full Load.}\\ \mbox{Upper: 50 } \mu\mbox{s / div, 10 mV / div.}\\ \mbox{Lower: 2 } \mu\mbox{s / div, 10 mV / div.} \end{array}$



 $\label{eq:Figure 25-Ripple, 48 VDC, Full Load.} Upper: 50 \ \mu\text{s} \ / \ div, \ 10 \ m\text{V} \ / \ div.} \\ \text{Lower: 2 } \mu\text{s} \ / \ div, \ 10 \ m\text{V} \ / \ div.}$



11 Revision History

Date	Author	Revision	Description & changes
January 3, 2006	RM/LN/ME	1.0	Initial release
April 13 2006	RM	1.1	Updated photo, layout,
			schematic and BOM



Notes



Notes



Notes



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